

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Rost et al. Art Unit: 2811  
Serial No.: 10/696,816 Examiner: Crane, S.  
Filing Date: 10/30/2003 Docket No.: TI-35257  
Customer No.: 23494 Conf. No.: 1301  
Title: ONE MASK HIGH DENSITY CAPACITOR FOR INTEGRATED CIRCUITS

**RESPONSE UNDER EX PARTE QUAYLE**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

The following remarks are offered in response to the Examiner's Office Action dated November 2, 2006. They are respectfully submitted as a full and complete response to that Action.

**REMARKS**

Reconsideration of the above-referenced application in view of the following remarks is respectfully requested.

Claims 2 and 4-10 stand allowed.

Claims 2 and 4-10 are objected to due to an informality regarding the meaning of the term "cap layer". As noted by the Examiner and in the instant specification at paragraph [0013], cap layer 118 provides a bonding surface which offers better adhesion for ball bonds, bond wires, etc. than copper and while the aluminum cap layer is metal, it is not considered a metal interconnect level, but merely a capping layer to